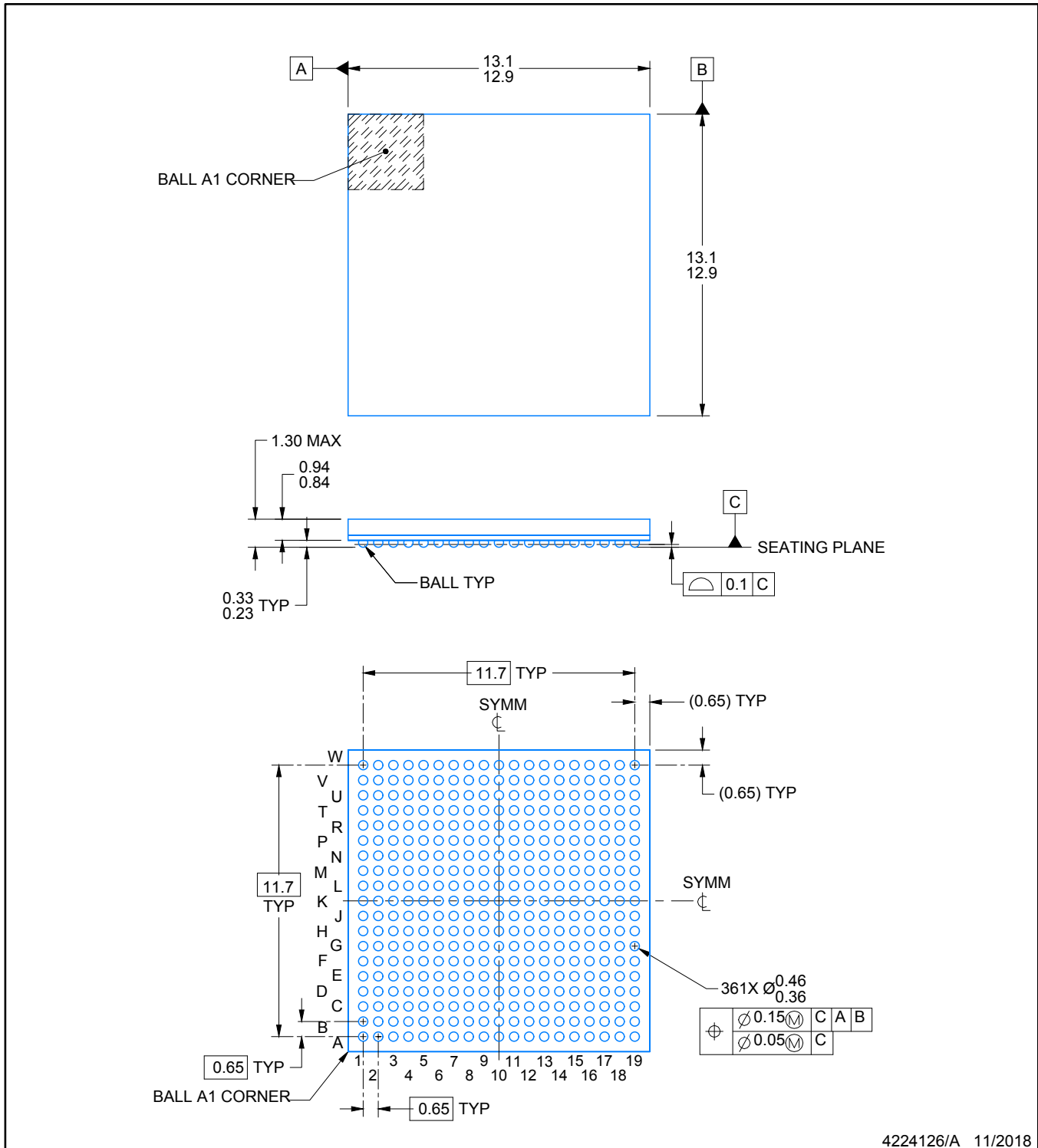


# PACKAGE OUTLINE

ZCE0361A

NFBGA - 1.30 mm max height

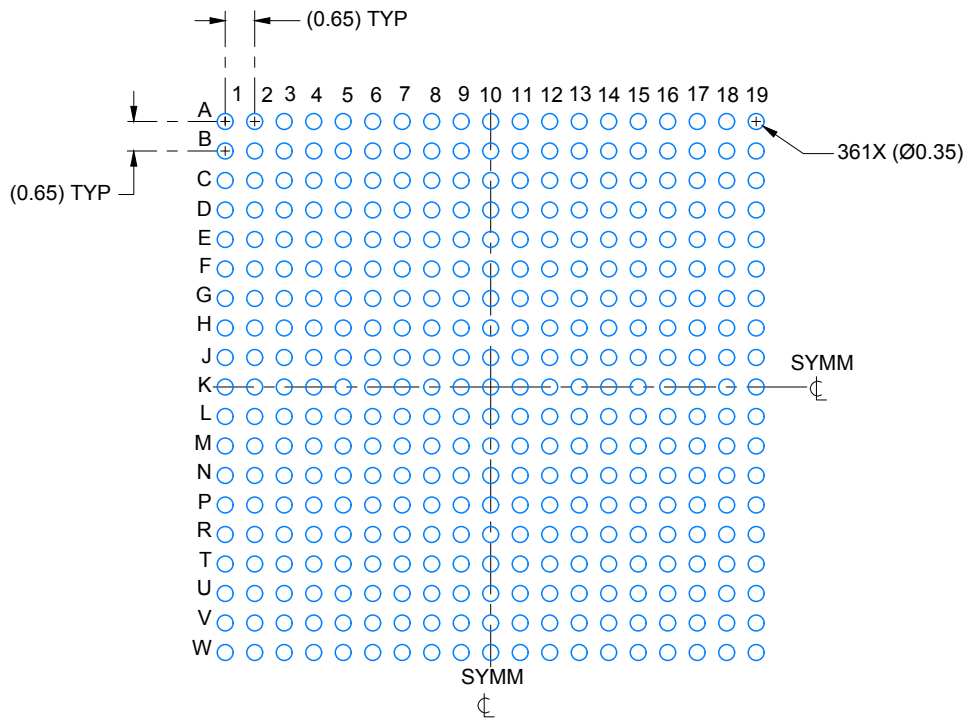
PLASTIC BALL GRID ARRAY



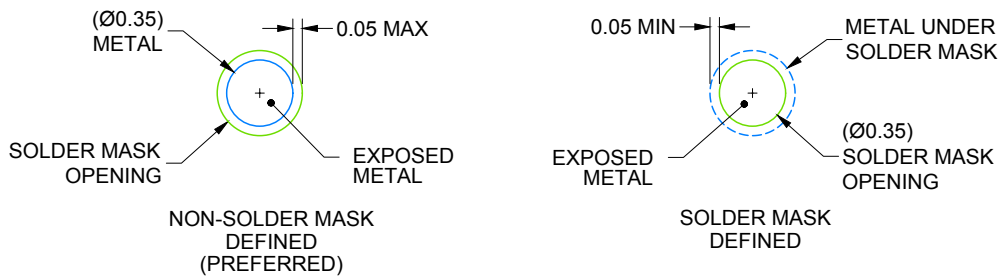
4224126/A 11/2018

**NOTES:**

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



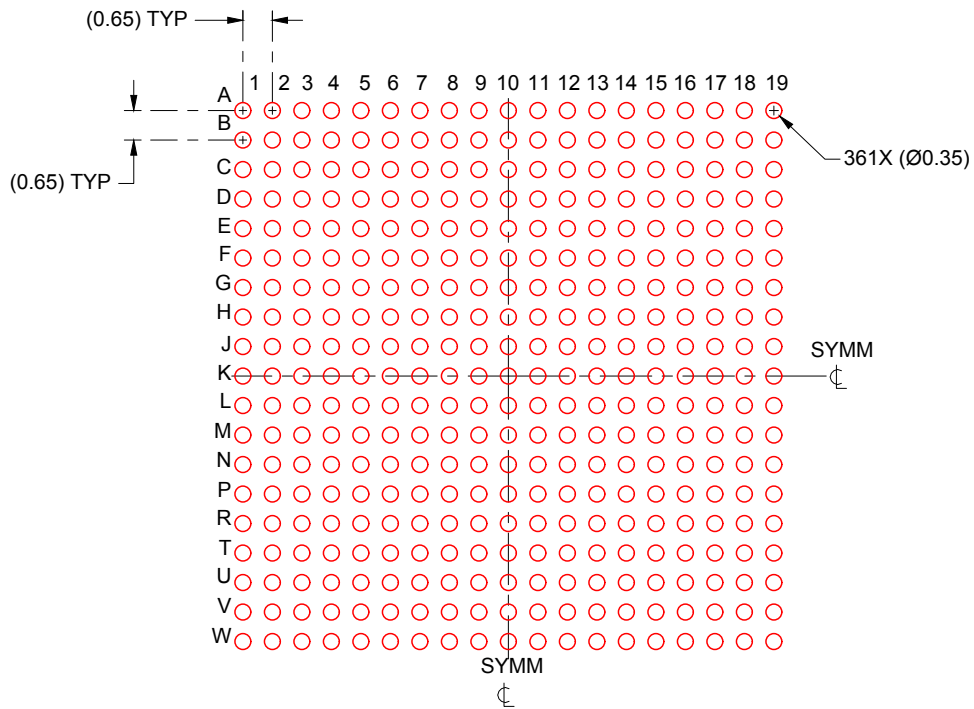
LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 6X



SOLDER MASK DETAILS  
NOT TO SCALE

NOTES: (continued)

3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For information, see Texas Instruments literature number SPRAA99 ([www.ti.com/lit/spraa99](http://www.ti.com/lit/spraa99)).



SOLDER PASTE EXAMPLE  
 BASED ON 0.125 mm THICK STENCIL  
 SCALE:6X

NOTES: (continued)

- 4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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